

**IN THE CLAIMS:**

Amend claim 9 pursuant to 37 C.F.R. §1.121 as follows:

9. (Thrice Amended) A method for the manufacture of a copper microalloy containing lead, comprising:

81 (a) mixing a copper alloy containing S, Se, As, Sb, Bi, Sn, Zn, Ni, Fe, Ag, or Te impurities in amounts of the order of tens of weight ppm with lead to yield a microalloy having at least 200 weight ppm of lead, wherein the copper alloy contains Zn, Fe, Ni, Sn, and Ag impurities in amounts of the order of tens of weight ppm;

(b) continuous casting the microalloy from step (a); and

(c) heating the microalloy from step (b) at 550-650° C for 5-600 seconds to decrease its half-softening temperature, annealing temperature, and recrystallization temperature to below 200° C.

**REMARKS**

Reconsideration of this application is requested. Claim 9 has been amended to remove the limitation that the microalloy contain less than 80 weight ppm of the impurities Zn, Ag, Cd, Sb, Ni, Fe, Bi, Sn and S. Claims 5, 7-12, 14, 15, 17-19, 21, and 22 are pending and at issue.

Claims 5-8 and 15-22 have been rejected under 35 U.S.C. §103(a) as obvious over Japanese Patent Publication Nos. 62047443 (JP '443) and 61133351 (JP '351). Claims 5-22 have been rejected under 35 U.S.C. §103(a) as obvious over Japanese Patent Publication Nos. 10195562 (JP '562) or 09078162 (JP' 162).